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Mail Stop Patent Applications Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Enclosed for filing are the following patent application papers:

Docket No.: DP-310331

Inventors : ROGER A MOCK ERICH W. GERBSCH

Title : DUAL-SIDED SUBSTRATE INTEGRATED CIRCUIT PACKAGE INCLUDING A LEADFRAME HAVING LEADS WITH INCREASED THICKNESS

Filing Fee Formula

Basic Fee\$	770.00
Additional Fees:	
Number of independent claims in excess of 3, times \$86.00\$	0.00
Number of claims in excess of 20, times \$18.00\$	0.00
Multiple dependent claim, add \$290.00	0.00
Total Filing Fee\$	770.00

The patent specification DP-310331 entitled DUAL-SIDED SUBSTRATE INTEGRATED CIRCUIT PACKAGE INCLUDING A LEADFRAME HAVING LEADS WITH INCREASED THICKNESS and filed in the Patent and Trademark Office herewith is the patent specification for which the inventor(s) executed the Declaration enclosed herewith.

Please charge the \$ 770.00 filing fee to DELPHI TECHNOLOGIES INC. Deposit Account No. 50-0831.

STEFAN V. CHMIELEWSKI Reg. No. 39941 (248) 813-1220

Enclosures

I hereby certify that this document is being deposited with the United States Postal Service with sufficient postage as Express Mail addressed to Commissioner for Patents, Alexandria, VA 22313-1450 on February 17, 2004 Express Mail Label EV3397679986US

<u>mita</u> <u>C. Beall</u> Signature